4 Circuit Performance

Figure 3 shows a low-frequency sweep for measuring the radiated emissions to demonstrate compliance with the EN55022 standard, which specifies the limits and methods of measurement of radio disturbance characteristics of information technology equipment.

Figure 3. Radiated Emissions (dBµV/m) from 10 kHz to 30 MHz

Figure 4 shows the circuit efficiency over load current. Although load currents in the lower 20 mA can be expected for low data rates and no common-mode voltage, higher load currents around 100 mA are required for high data rates and high common-mode voltages.

Figure 4. Efficiency Over Load Current
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